507474655 09/06/2022

### **PATENT ASSIGNMENT COVER SHEET**

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT7521548

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
Wei-Kang Fan	08/18/2022
Tung-Min Lin	08/18/2022

### **RECEIVING PARTY DATA**

Name:	Realtek Semiconductor Corp.
Street Address:	2 Innovation Rd. II, Science Park
City:	HsinChu
State/Country:	TAIWAN

### **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	17903059

### **CORRESPONDENCE DATA**

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Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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ATTORNEY DOCKET NUMBER:	REAP1295USA
NAME OF SUBMITTER:	VICKIE LEE
SIGNATURE:	/VICKIE LEE/
DATE SIGNED:	09/06/2022

**Total Attachments: 4** 

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PATENT 507474655 REEL: 060988 FRAME: 0454

## COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

### Title of Invention:

### MULTI-LINK DEVICE ADOPTING BLOCK ACKNOWLEDGMENT AND PACKET ALLOCATION METHOD THEREOF

As the below named inventor, I hereby declare that: This declaration is directed to:				
☑ The attached application, or				
☐ United States application number	filed on	, or		
☐ PCT international application number	filed on			
The above-identified application was made or authorized to be r	made by me.			
I believe that I am the original inventor or an original joint inventa application.	or of a claimed invention in	the		
I hereby acknowledge that any willful false statement made in thunder18 U.S.C. 1001 by fine or imprisonment of not more than f		e		
In consideration of the payment by Realtek Semiconduct	or Corp. having a po	stal address of		
2 Innovation Rd. II, Science Park, HsinChu 30076, Ta	aiwan, R.O.C.			
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.				
I hereby sell, assign and transfer to ASSIGNEE and the successors and assignees of the ASSIGNEE the entire right, title and interest in and to any and all improvements which are disclosed in the invention as above-identified application and, in and to, all Letters Patent to be obtained for said invention by the above application or any continuations, continuation-in-part, divisions, renewals, substitutes, or extensions thereof, and as to Letters Patent any reissue or re-examination thereof.				
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said invention and said Letters Patent and legal equivalents as may be known and accessible to I and will testify as to the same in any interference, litigation proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal				
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for each additional inventor.				

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NPO#REA-P1295-USA:0 CUST#110A-355US F#NPO-P0002E-US1201 DSB0-111U003245

### Docket No REAP1295USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor:

Wei-Kang Fan

Date:

AUG 18 2022

Signature:

Wei-Kang Fan

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F#NPO-P0002E-US1201 DSB0-111U003245

NPO#REA-P1295-USA:0 CUST#110A-355US

> PATENT REEL: 060988 FRAME: 0456

# COMBINE DECLARATION (37 CFR 1.63) FOR UTILITY OR DESIGN APPLICATION USING AN APPLICATION DATA SHEET (37 CFR 1.76) AND ASSIGNMENT

### Title of Invention:

### MULTI-LINK DEVICE ADOPTING BLOCK ACKNOWLEDGMENT AND PACKET ALLOCATION METHOD THEREOF

As the below named inventor, I here This declaration is directed to:	eby declare that:			
☑ The attached application, o	r			
☐ United States application number		filed on	, or	
☐ PCT international application number		filed on	water to the state of the state	
The above-identified application was	s made or authorized to be made	e by me.		
I believe that I am the original invenapplication.	tor or an original joint inventor of	f a claimed invention in the	he	
I hereby acknowledge that any willfu under18 U.S.C. 1001 by fine or imp	ul false statement made in this d risonment of not more than five (	eclaration is punishable (5) years, or both.		
In consideration of the payment by	Realtek Semiconductor C	Corp. having a post	tal address of	
2 Innovation Rd. II, Science P	Park, HsinChu 30076, Taiw	an, R.O.C.		
(referred to as "ASSIGNEE"below) to I of the sum of One Dollar (\$ 1.00), the receipt of which is hereby acknowledged, andfor other good and valuable consideration.				
I hereby sell, assign and transfer to the entire right, title and interest in a invention as above-identified applica- invention by the above application of substitutes, or extensions thereof, a	ind to any and all improvements ation and, in and to, all Letters P or any continuations, continuation	which are disclosed in the Patent to be obtained for some n-in-part, divisions, renev	ne said wals,	
I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment;				
I further covenant that ASSIGNEE wand documents relating to said inveknown and accessible to I and will terelated thereto and will promptly exe	ntion and said Letters Patent and estify as to the same in any inter	id legal equivalents as ma rference, litigation procee	ay be	
representatives any and all papers, instruments or affidavits required to apply for, obtain, maintain, issue and enforce said application, said invention and said Letters Patent and said equivalents thereof which may be necessary or desirable to carry out the proposes thereof. IN WITNESS WHEREOF, I have hereunto set hand and seal this on the date(s) indicated.				
Note: An application data sheet (PTO/SB/14 or equivalent), including naming the entire inventive entity, must accompany this form. Use this form for <u>each additional inventor.</u>				

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NPO#REA-P1295-USA:0 CUST#110A-355US F#NPO-P0002E-US1201 DSB0-111U003245

### Docket No REAP1295USA

LEGAL NAME OF INVENTOR(ASSIGNOR)

Inventor: Tung-Min Lin Date: AUG 18 2022

Signature: Tung-Min Lin

NPO#REA-P1295-USA:0 CUST#110A-355US

**RECORDED: 09/06/2022** 

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F#NPO-P0002E-US1201 DSB0-111U003245

PATENT REEL: 060988 FRAME: 0458